

Product Application

TechiEtch CN10 is an highly tunable, effective & selective metal etchants for UBM, RDL and Cu pillar applications.

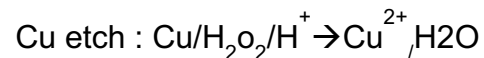
TechniEtch CN10 is an acidic based metal etchant, containing particular additives that greatly enhance stability and metal loading capability compared to conventional oxidative acidic based solutions.

TechniEtch CN10 is designed to etch both Ni and Cu metal layers.

POU version

- Blend ingredients in a vessel equipped with agitation, blowhole
 - See material compatibility
 - For sampling (<1 gallon), ingredient can be mixed up within the bottles itself while following the mixing instructions hereafter.
 - All vessels, tubing, filters should be free of organic and metallic contaminations

- Recommended Mixing Temperature: 15-25°C
- The amount of peroxide to be added into the TechniEtch CN10 POU solution would depend of the Cu etch rate required.
- The Cu etch rate would mainly depend of the peroxide content, temperature agitation and the propriety of the Cu layer itself (see process information)
- The standard peroxide spike added to the TechniEtch CN10 is 10 to 15 Wt% of H2O2 (30%) and can be adjusted accordingly.

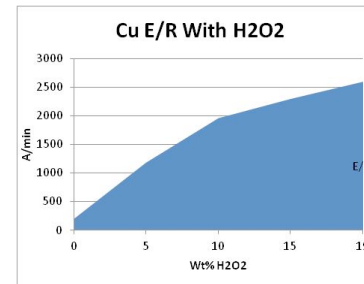


Process information

Etch rate key factors:

Equipment- immersion Vs batch
Static Vs dynamic
Temperature

All those process parameters and set up must be carefully monitored and controlled to get repeatable etch rate



Cu etch rate f(H2O2)

Metal	static	Dynamic
Ni*	0.1-10**	>2
Cu*	0.02-10**	>0.05
Ti/TiN	<1	<1

Etch rate @ 23C in µm/min
Material and process dependent

TECHNIC France

15, rue de le Montjoie – BP 79 –
93212 SAINT DENIS LA PLAINE CEDEX
Tel: +33 1.49.46.51.00 – Fax: +33 1.48.20.55.30
technic.france@technic.fr
www.technic.com/eu/